

PCN: V11-015-48475412-0A

Product Change Notice

Issue Date: 1st Feb 2011

Change Type:

Please be advised that Avago Technologies is making the following product change on the effective date noted for the products listed below.

Fab Related Change: New die source

Parts Affected:

The list of part numbers affected by the change are
HLMP-S100
HLMP-R100

Description and Extent of Change:

The above part number will be use new dice source.

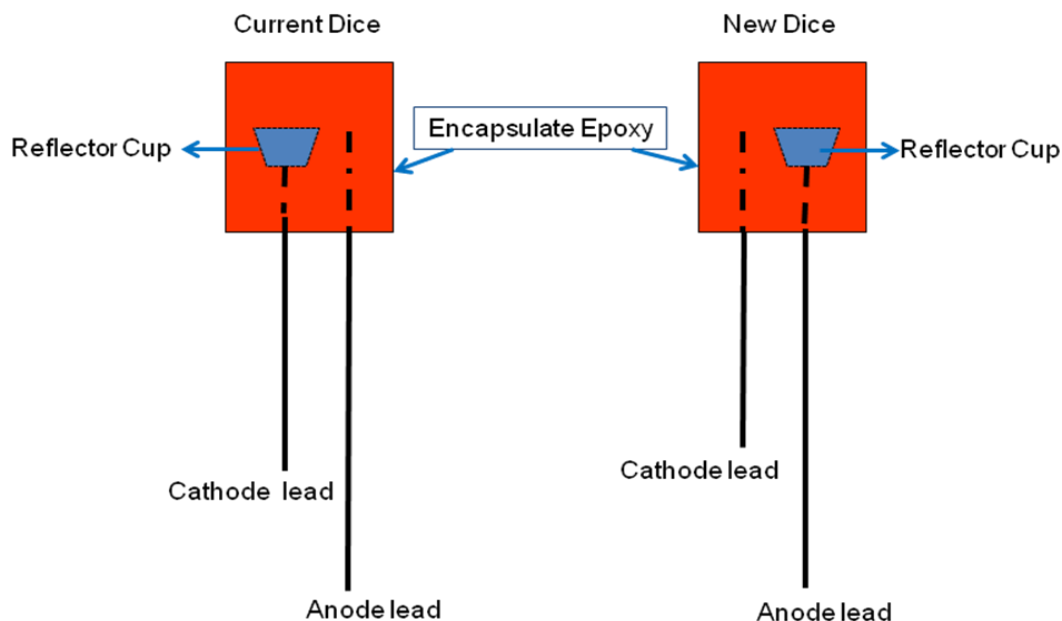
Reasons for Change:

This is to ensure consistency of dice supply chain.

Effect of Change on Fit, Form, Function, Quality, or Reliability:

There is no change in fit , function , quality and reliability on this product. Qualification and characterization have been conducted using the new die to ensure similar performance as existing products. With the new die source there will be changes as below.

Appearance Comparison





Effective Date of Change:

Shipment with new dice source will start on 1st May 2011 onward. There will be combination shipments between current and new dice source during transition period.

Qualification Data:

HLMP-R100, HLMP-S100

Environmental/Life Test	Reference	Stress Profile	Unites Tested	Units Failed
Temperature Cycling	Avago Std	-40/100°C 15/5min Dwell/Transfer, 100cyc	384 x 2	0
High Temperature Operating Life	JESD22-A108	70°C, Max Derated Current, 1000hrs	84 x 2	0
High Temperature Humidity Storage	Avago Std	85°C, 85% RH, 1000hrs	84 x 2	0

These changes have been reviewed and approved by Avago Technologies engineers and managers per Avago Technologies procedure: Change Control and Customer Notification, A-5962-6052-80.

Please contact your Avago Technologies field sales engineer or Contact Center (<http://www.avagotech.com/contact/>) for any questions or support requirements. Please return any response as soon as possible, but not to exceed 30 days.